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(21) International Application Number: PCT/US97/07191 (22) International Filing Date: 1 May 1997 (01.05.97) (30) Priority Data: 60/016,665 1 May 1996 (01.05.96) US 08/846,380 30 April 1997 (30.04.97) US (71) Applicant: ALLIEDSIGNAL INC. [US/US]; 101 Columbia Road, P.O. Box 2245, Morristown, NJ 07962-2245 (US). (72) Inventors: FATCHERIC, John, F.; 710 Freedom Street, Holmen, WI 54636 (US). CARBIN, Derek, C.; 10 Blackberry Lane, Bennington, VT 05201 (US). (74) Agent: CRISS, Roger, H.; AlliedSignal Inc., Law Dept. (C.A. McNally), 101 Columbia Road, P.O. Box 2245, Morristown, NJ 07962-2245 (US).		(81) Designated States: AL, AU, BB, BG, BR, CA, CN, CU, CZ, EE, GE, HU, IL, IS, JP, KP, KR, LK, LR, LS, LT, LV, MG, MK, MN, MW, MX, NZ, PL, RO, RU, SD, SG, SI, SK, TR, TT, UA, UZ, VN, ARIPO patent (GH, KE, LS, MW, SD, SZ, UG), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i> <i>Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i>

(54) Title: NEW METHOD OF FORMING FINE CIRCUIT LINES**(57) Abstract**

A new method of forming circuit lines on a substrate by applying conductive metal(s) using copper foil as a carrier. The copper foil is etched away, leaving the conductive metals embedded in the surface of the substrate. A photoresist is used to expose trenches which define the desired circuit and copper is applied onto the exposed conductive metals. The method is particularly suited to manufacturing the outer layers of multi-layer circuit boards.